Nov. 13, 2019 (Wed.)		
19:00-20:30	**Welcome Reception**	
Nov. 14, 2019 (Thu.)		
	Orion Room, 3F	**Grand Ballroom, 2F**
08:00-09:30	**A1. Solder and Bump 1**	**B1. Heterogeneous Integration 1**
Session chair	Hiroshi Nishikawa (Osaka University/ Japan)	Suck Won Hong (Pusan National University/ Korea)
08:00-08:25	**(Invited) I1-1 Recent Advances in Underfill for Flip Chip Applications**	**(Invited) I1-2 Technology and Market Trends of Advanced SiP**
	Osamu Suzuki (NAMICS Corp./ Japan)	Santosh Kumar (Yole Développement/ France)
08:25-08:50	**(Invited) I1-3 Development of Materials Informatics Platform**	**(Invited) I1-4 A Perspective on Heterogeneous Integrated Edge Devices for Industry Internet of Things (IIOT) to Support Smart Manufacturing**
	Yasumitsu Orii (NAGASE & CO., LTD./ Japan)	G.P. Li (University of California, Irvine/ USA)
08:50-09:10	**O1-1 Microstructure and Solderability of Sn-Cu Solder Coatings Processed by Pulse Electrodeposition from a Stannate Bath**	**O1-2 Technical Issues and their Solutions of Laser-Assisted Bonding Technology**
	Ashutosh Sharma (Ajou University/ Korea)	Jiho Joo (ETRI/ Korea)
09:10-09:30	**O1-3 Advances in Metrology for Lead-free Solder Electroplating Bath**	**O1-4 Reactive Bonding by Integrated Nanostructured Al/Pd Multilayer Thin Film Systems for MEMS Packaging Applications**
	Jong Woung Kim (ECI Technology/ USA)	El-Mostafa Bourim (National NanoFab Center/ Korea)
09:30-09:45	***Coffee break***	
09:45-11:00	**A2. Taiwan Session 1**	**B2. Heterogeneous Integration 2**
Session chair	Yoonchul Sohn (Chosun University/ Korea)	Sungdong Kim (Seoultech/ Korea)
09:45-10:10	**(Invited) I1-5 Adhesion Enhancement through Co-Silanization-Assisted Metallic Immobilization on Flexible Polyimide**	**(Invited) I1-6 Manufacturing Technology Solution of Wafer / Panel Level Packaging for Heterogeneous Integration.**
	Chih-Ming Chen (National Chung Hsing University/ Taiwan)	Yasuhiro Morikawa (Ulvac, Inc./ Japan)
10:10-10:35	**(Invited) I1-7 Enhancement of Nano-Silver Chip Attachment by Using Transient Liquid Phase Reaction with Indium**	**(Invited) I1-8 Fabrication of Fine Pattern with Imprint Technique**
	C. Robert Kao (National Taiwan University/ Taiwan)	Katsumi Miyama (Hokkaido University of Science/ Japan)
10:35-11:00	**(Invited) I1-9 An Investigation on Scribing and Etching the Thin-Film Stainless Steel Substrate using Ultrafast Laser**	**(Invited) I1-10 Ultimate 3D Package Solution by FO / PLP Technology**
	Hsiang-Chen Hsu (I-Shou University/ Taiwan)	Yun Mook Park (Nepes Corp./ Korea)
11:00-11:10	***Break***	
11:10-11:20	**Opening Ceremony**	
Session chair	Hee-Yeoun Kim (National NanoFab Center/ Korea)	
11:20-12:10	**Plenary Talk 1 (Grand Ballroom, 2F)** **The Future of Electronic Packaging Industry** **Sayoon Kang (Samsung Electro-Mechanics/ Korea)**	
12:10-13:30	***Lunch***	
Session chair	Taek-Soo Kim (KAIST/ Korea)	
13:30-14:10	**Keynote Talk 1 (Grand Ballroom, 2F)** **Advanced Packaging Technologies and Reliability Challenges for Exa-Era Applications** **Kang-Wook Lee (SK Hynix/ Korea)**	
14:10-14:50	**Keynote Talk 2 (Grand Ballroom, 2F)** **Electroplated Cu Bump with Ultra-Large Grain without Thermal Annealing and Kirkendall Void at the Interface of Cu/Sn Joint** **Wei-Ping Dow (National Chung Hsing University/ Taiwan)**	
14:50-15:05	***Coffee break***	

15:05-16:20	A3. Flexible & LED Packaging	B3. Wearable Electronics 1
Session chair	Byoung Joon Kim (Andong National University/ Korea)	C. Robert Kao (National Taiwan University/ Taiwan)
15:05-15:30	**(Invited) I1-11 Silicon-Based Flexible Electronics Enabled by HANAflex**	**(Invited) I1-12 A Study on the Dynamic Bending Reliability of Chip-in-Flex (CIF) Packages using Anisotropic Conductive Films (ACFs) Materials for Wearable Electronic Applications**
	Jae-Sung Lim (HANA Micron Inc./ Korea)	Kyung W. Paik (KAIST/ Korea)
15:30-15:55	**(Invited) I1-13 LED Packaging Trend & Super Strong + Ultra Tough LED**	**(Invited) I1-14 Soft, Thin Skin-Mounted Power Management Systems for Healthcare Monitoring**
	Onishi Tetsuya (Grand Joint Technology Ltd./ Japan)	Jung Woo Lee (Pusan National University/ Korea)
15:55-16:20	**(Invited) I1- 15 Recent Microdisplay Technology Status for AR/VR Applications**	**(Invited) I1-16 Transient Electronics**
	Hyunkoo Lee (ETRI/ Korea)	Suk-Won Hwang (Korea University/ Korea)
16:20-16:35	***Coffee break***	
16:35-17:25	A4. Solder and Bump 2	B4. Wearable Electronics 2
Session chair	Sehoon Yoo (KITECH/ Korea)	Katsumi Miyama (Hokkaido University of Science/ Japan)
16:35-17:00	**(Invited) I1-17 Transient Liquid Phase Bonding using Sn-coated Cu Particles for High-Temperature Applications**	**(Invited) I1-18 Unventional Bio-integrated Electronics towards Human-machine Interface (HMI) Applications**
	Hiroshi Nishikawa (Osaka University/ Japan)	Ki Jun Yu (Yonsei University/ Korea)
17:00-17:25	**(Invited) I1-19 Micro-Nano Joining by Nano Silver Sintering in Power Electronic Packaging**	**(Invited) I1-20 Nanocrystal Based Electronic Devices and Wearable Sensors**
	Mingyu Li (Harbin Institute of Technology/ China)	Soong Ju Oh (Korea University/ Korea)
17:25-18:30	**Poster Presentation Session 1 (Jupiter Room, 3F)** Session chair: Sungdong Kim (Seoultech/ Korea)	
18:30-21:00	***Banquet (Grand Ballroom, 2F)***	
Nov. 15, 2019 (Fri.)		
	Orion Room, 3F	**Grand Ballroom, 2F**
08:00 - 09:45	C1. Advanced Packaging	D1. Electronic Materials
Session chair	Ben-Je Lwo (National Defense University/ Taiwan)	Changhwan Choi (Hanyang University/ Korea)
08:00-08:25	**(Invited) I2-1 FOWLP-based Flexible Hybrid Sensor Systems with Dielets and 3D-IC**	**O2-1 Good Wettability and Mechanical Strength of Sn-3Ag-0.5Cu Solders on Ni Plated ZnS Ceramics**
	Takafumi Fukushima (Tohoku University/ Japan)	Shuye Zhang (Harbin Institute of Technology/ China)
08:25-08:45	**O2-2 Compact Yagi-Uda-Shaped and Array Antenna in Ka-Band Using Compressed EBG Unit Cells**	**O2-3 Crystallinity Dependence of Grain and Grain Boundary Strength in Polycrystalline Copper Interconnections**
	Jae-Yeong Lee (Pohang University of Science and Technology/ Korea)	Ken Suzuki (Tohoku University/ Japan)
08:45-09:05	**O2-4 New Paradigm in Silicon Capacitors Assembly used as Decoupling Capacitors**	**O2-5 Study on mold gap fill association factor of epoxy molding compound for thin package**
	Muller Charles (KOREA MURATA Electronics Co.,Ltd/ France)	Jun Shin Lee (SK Hynix/ Korea)
09:05-09:25	**O2-6 A Study on Improving Flexibility for Chip Stackable Flexible Package**	**O2-7 Low Dielectric Materials for High-Speed Transmission**
	Kyoungtae Eun (SK Hynix/ Korea)	Shin TERAKI (NAMICS Corp./ Japan)
09:25-09:45	**O2-8 Role of Wafer Support System for Advanced Packaging**	**O2-9 Comprehensive Stress Effects Induced by Through Silicon Via Integrated with Local S/D Stressor on Performances of Nano-Scaled Devices in Silicon Interposer Architecture**
	KiYeul Yang (Amkor technology korea/ Korea)	Yan-Cian Lin (National Tsing Hua University/ Taiwan)

09:45-10:00	***Coffee break***	
Session chair	Kwang-Seong Choi (ETRI/ Korea)	
10:00-10:50	**Plenary Talk 2 (Grand Ballroom, 2F)** **Wafer Level 3D Application for Tera-byte Node** **Takayuki Ohba (Tokyo Tech/ Japan)**	
10:50-11:30	**Keynote Talk 3 (Grand Ballroom, 2F)** **From Monolithic to Polylithic Integrated Circuits: A New Age for Moore's Law** **Muhannad S. Bakir (Georgia Tech/ US)**	
11:30-12:10	**Keynote Talk4 (Grand Ballroom, 2F)** **Could the Reliability of Solder Joints be Assessed Accurately by Using the Weibull Distribution?** **Sung Yi (Portland State University/ US)**	
12:10-13:30	***Lunch***	
13:30-15:30	**C2. Young Scientists**	**D2. Taiwan Session 2**
Session chair	Ken Suzuki (Tohoku University/ Japan)	Sung-Hoon Choa (Seoultech/ Korea)
13:30-13:50	**(Y/S) O2-10 A First Principle Study on the Localized Electronic Band Structure of a Single Long Graphene Nanoribbon with Graphene Electrodes**	**O2-11 Electrospinning Opportunity for Wearable Thermoelectric Generator**
	Qinqiang Zhang (Tohoku University/ Japan)	Ben-Je Lwo (National Defense University/ Taiwan)
13:50-14:10	**(Y/S) O2-12 Convolution Neural Network Based Diagnosis of Temperature Sensors in a Bake Module**	**O2-13 AI-Assisted Design-on-Simulation Technology for Advanced Packaging**
	Jinwoo Lee (Sungkyunkwan University/ Korea)	Bo-Ruei Lai (National Tsing Hua Univ./ Taiwan)
14:10-14:30	**(Y/S) O2-14 Photoresponsivity of a Graphene Nanoribbon based Field Effect Transistor for the Development of a Multi-Junction Solar Cell using a Single Material**	**(Y/S) O2-15 Process-induced Warpage Characterization of Flip Chip Package on Packaging**
	Jowesh Goundar (Tohoku University/Japan)	Ling-Ching Tai (Feng Chia University/Taiwan)
14:30-14:50	**(Y/S) O2-16 Effect of Surface Treatments on the Interfacial Adhesion of Cu RDL for FOWLP**	**(Y/S) O2-17 Thermally-Induced Curvatures and Warpages of 2.5D Packages Measured by Strain Gauge**
	Kirak Son (Andong National University/ Korea)	Ms. Y. W. Wang (Chang Gung University/ Taiwan)
14:50-15:10	**(Y/S) O2-18 Low Temperature Wafer-Scale Si Layer Transfer by Wafer Bonding for the 3D Integration**	**(Y/S) O2-19 Reliability Prediction of WLCSP using RF Regression Model**
	Hoonhee Han (Hanyang University/ Korea)	Mr. T.H. Tsai (National Tsing Hua University/ Taiwan)
15:10-15:30	**(Y/S) O2-20 Advanced Nanofilm Transfer Methods by Water**	**(Y/S) O2-21 Determination of Thin Silicon Die Strength by Three-Point Bending**
	Sumin Kang (KAIST/ Korea)	Mr. H. Y. Liu (Chang Gung University/ Taiwan)
15:30-16:30	**Poster Presentation Session 2 (Jupiter Room, 3F)** Session chair: Daeil Kwon (Sungkyunkwan University/ Korea)	
16:30-17:00	**Award Ceremony and Closing Remark (Lucky Draw) (Grand Ballroom, 2F)**	

※ **EMAP Steering Committee Meeting**: Nov.14, 2019 (Thu.) PM12:00, Venus Room (3rd Floor)
※ **Annual Meeting**: Nov.15, 2019 (Fri.) PM12:10, Venus Room (3rd Floor)

Poster Presentation Session I - Nov. 14, 2019 (Thu.), Jupiter Room, 3F					
No.	Topic	First Author	Affiliation (First Author)	Country	Paper Title
P1-01	1. Advanced Packaging Technologies	Youngil Kim	Seoul National University of Science and Technology	kr	Low Temperature Bonding using a Laser for Flexible Electronic Devices
P1-02	1. Advanced Packaging Technologies	Min kyu Kang	SK Hynix	kr	Study on Viscoelastic Material Properties of Epoxy Mold Compound to Improve the Accuracy of Package Warpage Simulation
P1-03	1. Advanced Packaging Technologies	Gahui Kim	Andong National University	kr	Ar/N_2 Plasma Treatment Effect on Quantitative Interfacial Adhesion Energy of Sputtered Cu Direct Bonding for 3-D Integration
P1-04	1. Advanced Packaging Technologies	Kwang Ho Ahn	Korea Advanced Institute of Science and Technology (KAIST)	kr	Effect of Femtosecond Laser Machining Environment on Mechanical Behaviors of Thinned Silicon
P1-05	10. Design Tools and Modeling	Sungdong Kim	Seoul National University of Science and Technology	kr	Panel Level Warpage Analysis with Various RDL Layouts
P1-06	2. Electronic Materials for Interconnects and Packaging	Dain Lim	Korea Institute of Industrial Technology (KITECH)	kr	Characterization of the Viscosity Behavior of Electronic Packaging Adhesives
P1-07	2. Electronic Materials for Interconnects and Packaging	Jae-Hyeong Park	Korea Advanced Institute of Science and Technology (KAIST)	kr	Flexible Ultrasonic Transducer Packaging using Solder ACFs (Anisotropic Conductive Films)
P1-08	2. Electronic Materials for Interconnects and Packaging	HanMin Lee	Korea Advanced Institute of Science and Technology (KAIST)	kr	A Study of the Curing Behaviors and Viscosities of Non-Conductive Films (NCFs) on Flip Chip Solder Bump Joint Morphology and Reliability
P1-09	2. Electronic Materials for Interconnects and Packaging	Genta Nakauchi	Tohoku University	jp	Micro texture Dependence of Mechanical Damage Mechanism of Electroplated Gold Thin Film Used for Semiconductor Device Interconnections
P1-10	3. Emerging Process for Interconnects and Packaging	Sungdong Kim	Seoul National University of Science and Technology	kr	Plasma Pre-treatment for Low-Temperature Cu-Cu Direct Bonding
P1-11	3. Emerging Process for Interconnects and Packaging	Sungdong Kim	Seoul National University of Science and Technology	kr	Planarization of Polymeric Dielectrics for FOWLP
P1-12	4. PCB, Solder, and Assembly Process	Jungsoo Kim	Korea Institute of Industrial Technology (KITECH)	kr	Effects of Reaction Time and Pd Layer Type on Interfacial Reactions and IMC Morphologies of Thin-Au/Pd/Ni Surface Finished PCBs with Sn-3.0Ag-0.5Cu Solder Joints
P1-13	4. PCB, Solder, and Assembly Process	HyeJun Kang	University of Seoul	kr	Effect of Sn-Ni Solder on TLP Joint Properties of SiCfor Power Module
P1-14	5. Power Electronic Packaging	HYUNCHEOL BAE	Electronics and Telecommunications Research Institute (ETRI)	kr	High Thermal Conductive Cu Sintering Paste for xEV Power Module
P1-15	5. Power Electronic Packaging	Seungju Baek	Korea Institute of Industrial Technology (KITECH)	kr	Effect of Preform with Plasma Treatment on Joint of TLP Bonding
P1-16	5. Power Electronic Packaging	Dong Yun Jung	Electronics and Telecommunications Research Institute (ETRI)	kr	Switching Performances by Chip Interconnections in Power Semiconductor Discrete Packages
P1-17	6. Sensors, LED, and Emerging Packaging Technology	Sang-Pil Han	Electronics and Telecommunications Research Institute (ETRI)	kr	Novel Optical Biomedical Image Sensing Technique for Three-Dimensional Biological Inspection
P1-18	6. Sensors, LED, and Emerging Packaging Technology	Duyoung Choi	Korea Institue of Industrial Technology (KITECH)	kr	Biodegradably Coated Magnetic Nanocapsules for On-off Switchable Drug Release with Reduced Leakage
P1-19	6. Sensors, LED, and Emerging Packaging Technology	Sang Hyun Jung	Korea Advanced Nano Fab Center	kr	Transfer of Hall Sensor Materials using Low Temperature Gallium Arsenide-Silicon Wafer Eutectic Bonding
P1-20	6. Sensors, LED, and Emerging Packaging Technology	Jongkyu Won	Dankook University	kr	Improvement of Indirect X-ray Detector Performance by Applying Additive Solvent to the Organic Active Layer
P1-21	7. Wearable and Printed Electronics	Jong-Woong Kim	Chonbuk National University	kr	Stretchable and Thermally-healable Transparent Electrode Based on Diels-Alder Adducts for Stretchable Electronic Packages
P1-22	7. Wearable and Printed Electronics	se-hoon Park	Korea Electronics Technology Institute (KETI)	kr	A Wearable Photoplethysmogram(PPG) Sensor Using Flexible and Stretchable Substrate

P1-23	7. Wearable and Printed Electronics	Jang-Woo Han	Korea Institute of Industrial Technology (KITECH)	kr	A Study on the Coating Characteristics of VO2 Nanoparticle Film with Various Conditions of Ultrasonic Spray Coater
P1-24	7. Wearable and Printed Electronics	Ji Hun Yuk	Seoul National University of Science and Technology	kr	Stretchable and Flexible Transmission Line Based on Highly Conductive Silver Paste for Wearable Applications
P1-25	7. Wearable and Printed Electronics	Nam Hyun Jin	Dept. of Manufacturing Systems and Design Engineering	kr	Development of Mechanical Characteristics of Possible Stretchable Electrodes Applied to Stretchable/Flexible Display
P1-26	7. Wearable and Printed Electronics	Junhyuk Son	Korea Institute of Industrial Technology (KITECH)	kr	A Study on the Adhesion Characteristics between Polyimide and Metal Film by CO2 Laser Treatment
P1-27	7. Wearable and Printed Electronics	SangWoo Kim	Sungkyunkwan University	kr	Flexible and Stretchable Radio Frequency Antenna based on Silver Nanowires
P1-28	7. Wearable and Printed Electronics	Sungdong Kim	Seoul National University of Science and Technology	kr	Comparison of Interconnection Methods for E-textile Applications
P1-29	7. Wearable and Printed Electronics	Choong-Jae Lee	Sungkyunkwan University	kr	Fabrication of Printed Ag Circuits with Plasma Assisted-sintering Process and its Electrochemical Migration Behaviors
P1-30	7. Wearable and Printed Electronics	SangWoo Kim	Sungkyunkwan University	kr	Design of Cu Circuit for Stretchable Electronic Circuits using Finite Element Analysis
P1-31	8. MEMS/NEMS Packaging and Applications	ChungMo Yang	National NanoFab Center	kr	Fabrication of MEMS Gyro Sensor with Wafer Level Vacuum Packaging
P1-32	9. Reliability of Electronic Devices and Systems	Youngil Kim	Seoul National University of Science and Technology	kr	Analysis of Temperature Rise and Flexibility of Flexible Highly Efficient Compound Solar Module
P1-33	9. Reliability of Electronic Devices and Systems	Geum-Yong Park	Andong National University	kr	Mechanical Reliability of Conductive Yarn during Repeated Bending Deformation
P1-34	9. Reliability of Electronic Devices and Systems	Yong-Wook Kwon	Andong University Flexible Electronic Materials Laboratory	kr	Twisting Test of Interconnect on Flexible Polymer Substrate
P1-35	1. Advanced Packaging Technologies	Yu-Jin Li	National Chiao Tung University	tw	High Reliability Fan-Out Redistribution Layer with Nano-scaled Twinning Structure
P1-36	1. Advanced Packaging Technologies	Chang Chih Hsieh	National Chiao Tung University	tw	Anisotropic grain growth in Cu joints at low temperatures by 111-oriented nanotwinned copper films
P1-37		Jun-Seok Ha	Chonnam National University	kr	Porous Copper-Graphene-Graphene Oxide Composite for Thermal Management of Nanoelectronics
P1-38	9. Reliability of Electronic Devices and Systems	Yeong-Kook Kim	Inha University	kr	Stress Development Analyses of PBGA Chip under Random Vibration
P1-39	7. Wearable and Printed Electronics	Jungpil Kim	Korea Institute of Industrial Technology (KITECH)	kr	Distinguishing Zigzag and Armchair Edges on Graphene Nanoribbons by X-ray Photoelectron and Raman Spectroscopies
P1-40	6. Sensors, LED, and Emerging Packaging Technology	Kwang-Seok Kim	Korea Institute of Industrial Technology (KITECH)	kr	Effects of Cu-CNT Nanocomposite TIM on Optical Spectra of LED Lighting Applications

Poster Presentation Session II - Nov. 15, 2019 (Fri.), Jupiter Room, 3F

No.	Topic	First Author	Affilliation (First Author)	Country	Paper Title
P2-01	1. Advanced Packaging Technologies	Bo kung Joung	Hanyang University	kr	Electromagnetic Interference Shielding Effect of Double Layer Copper Patterns with Moisture Ventilation at Package Level
P2-02	1. Advanced Packaging Technologies	Soonyong Kwon	Korea Institute of Industrial Technology (KITECH)	kr	Effect of Reducing Agent on the Sinterability of Cu Paste
P2-03	1. Advanced Packaging Technologies	Sarah Eunkyung Kim	Seoul National University of Science and Technology	kr	Comparative Study of Plasma Treatment on Sputtered and Electroplated Cu Surfaces for Cu-to-Cu Bonding

P2-04	1. Advanced Packaging Technologies	Sarah Eunkyung Kim	Seoul National University of Science and Technology	kr	Copper Nitride Passivation by Ar-N2 Two Step Plasma Treatments for Low-Temperature Copper Bonding
P2-05	2. Electronic Materials for Interconnects and Packaging	Dal-Jin Yoon	Korea Advanced Institute of Science and Technology (KAIST)	kr	Effects of Surface Activated Monolayer (SAM) Treatment onConductive Particles in Anchoring Polymer Layer (APL)Anisotropic Conductive Films (ACFs) for Chip-on-Glass (COG) Interconnection
P2-06	2. Electronic Materials for Interconnects and Packaging	Jong-Hyun Lee	Seoul National University of Science and Technology	kr	Novel Die-Attach Method on Cu-Finish Metallization by Pressure-Assisted Sinter-Bonding in Air Using Cu Formate Paste
P2-07	2. Electronic Materials for Interconnects and Packaging	Minsu Park	Andong National University	kr	Bendability Test and Bending Fatigue Test of Metal Film on Flexible Substrate
P2-08	2. Electronic Materials for Interconnects and Packaging	Sri Harini Rajendran	University of Seoul	kr	Structural and Mechanical Properties of Eutectic Sn-Bi-Te Temperature Solder
P2-09	2. Electronic Materials for Interconnects and Packaging	Byeong-Uk Hwang	Sungkyunkwan University	kr	Effect of Epoxy Contents in Cu Hybrid Paste on the Mechanical and Electrical Properties of Cu-Cu Joint
P2-10	2. Electronic Materials for Interconnects and Packaging	Seung Jun Hwang	University of Seoul	kr	Mechnical Properties of Al2O3/Cu Active Metal Brazing for Electric Vehicle
P2-11	3. Emerging Process for Interconnects and Packaging	AESUN OH	Electronics and Telecommunications Research Institute (ETRI)	kr	Sealing Process for Transparent Solar Cell based on Thin Film of Silicon
P2-12	4. PCB, Solder, and Assembly Process	Haksan Jeong	Sungkyunkwan University	kr	Mechanical Reliability of Flip Chip Package with Cu-core Solder Ballunder Thermal Shock Test
P2-13	4. PCB, Solder, and Assembly Process	Wook Sang Jeon	University of Seoul	kr	Effect of Graphene Nanoplatelets on the Mechanical Properties of SAC Alloy
P2-14	4. PCB, Solder, and Assembly Process	Ki-Seok Jang	Electronics and Telecommunications Research Institute (ETRI)	kr	Laser Assisted Bonding Process Using with Hybrid Underfill Technology for Flexible PET Application
P2-15	4. PCB, Solder, and Assembly Process	HyeJun Kang	University of Seoul	kr	Fabrication of SiC Power Module by TLP Solders and Its Characteristics
P2-16	5. Power Electronic Packaging	Kwang-Ho Jung	Sungkyunkwan University	kr	Pressureless TLPS Bonding with Cu and Sn-58Bi Particles and its Corrosion Behavior
P2-17	5. Power Electronic Packaging	Byung-Suk Lee	Korea Institute of Industrial Technology (KITECH)	kr	Sintering Study of Cu Micro/Nano-Particle Mixed Pastes for Power Semiconductor Bonding Applications
P2-18	5. Power Electronic Packaging	Kyung Deuk Min	Sungkyunkwan University	kr	Transient Liquid Phase Sintering Bonding in Air using Cu and Sn-58Bi and its Bonding Reliability under High Temperature Condition
P2-19	6. Sensors, LED, and Emerging Packaging Technology	Tae Young Lee	Korea Institute of Industrial Technology (KITECH)	kr	Effect of Interfacial Intermetallic Compound on Thermal Resistance of Flip-Chip LED
P2-20	6. Sensors, LED, and Emerging Packaging Technology	Nam Hyun Jin	Dept. of Manufacturing Systems and Design Engineering	kr	Development and Research of Universally Applicable Stretchable Strain Sensor
P2-21	6. Sensors, LED, and Emerging Packaging Technology	Hailiang Liu	Dankook University	kr	Improved Sensitivity of Organic Photodetector by Adding Polar Solvent to the Hole Transport Layer for Indirect X-ray Detection
P2-22	6. Sensors, LED, and Emerging Packaging Technology	Saehong Kim	Dankook University	kr	Sensitivity Improvement of Quantum Dot-blended Hybrid Detector for indirect-type X-ray Imaging
P2-23	7. Wearable and Printed Electronics	Yan Pan	Korea Advanced Institute of Science and Technology (KAIST)	kr	Bending Properties of Anchoring Polymer Layer (APL) Anisotropic Films (ACFs) for Ultra-Fine Pitch Chip-on-Flex (COF) Packages
P2-24	7. Wearable and Printed Electronics	Park Jun hwan	Korea Institute of Industrial Technology (KITECH)	kr	Ag-PDMS Printing Process for Stretchable Electrodes
P2-25	7. Wearable and Printed Electronics	Nam Hyun Jin	Dept. of Manufacturing Systems and Design Engineering	kr	Large-Scale Rapid Laser Sintering of Highly Stretchable Electrode Using a Homogenized Rectangular Laser Beam
P2-26	7. Wearable and Printed Electronics	Nam Hyun Jin	Dept. of Manufacturing Systems and Design Engineering	kr	Intense Pulse Light Sintering of an Ag Microparticle-based, Highly Stretchable, and Conductive Electrode

P2-27	7. Wearable and Printed Electronics	Hae Jin Kim	Korea Electronics Technology Institute	kr	Implementation of the Array Antenna for 77 GHz Band Using T-junction and Series-fed Structure
P2-28	7. Wearable and Printed Electronics	Seung Jin Oh	Korea Advanced Institute of Science and Technology (KAIST)	kr	Mechanical Properties of Indium Tin Oxide (ITO) Transparent Conductors for Flexible Applications
P2-29	7. Wearable and Printed Electronics	Ji Hun Kim	Korea Advanced Institute of Science and Technology (KAIST)	kr	Enhancement of Movement Speed of Soft Actuator Utilizing Diamagnetic Levitation
P2-30	8. MEMS/NEMS Packaging and Applications	Youngmoon Jang	Seoul National University of science and technology	kr	Deformation of Package and Changes of Natural Frequency in MEMS Accelerometer at Elevated Temperatures.
P2-31	8. MEMS/NEMS Packaging and Applications	Cha Ji-Hoon	Seoul National University of Science and Technology	kr	Numerical Analysis of Pad Deformation and Penetration withFine Pitch MEMS Vertical Probe Tip
P2-32	9. Reliability of Electronic Devices and Systems	Eunsol Jo	Kangnam University	kr	Study on Flame-retardant Coating of PET-based Module to Prevent Embers
P2-33	9. Reliability of Electronic Devices and Systems	Jaegeun Seol	Andong National University	kr	Fatigue Resistance and the Adhesion Properties of Cu Films on Polyimide Substrate Treated by Oxygen Plasma
P2-34		Myung Yung Jeong	Pusan National University	kr	Characteristics of Diffusive Transport with use of Metasurfaces for the Spatial Resolution Enhancement of fNIRS
P2-35		Myung Yung Jeong	Pusan National University	kr	Multiple Solutions of Thin Film Coating on Horizontal Rotating Cylindrical Mold by Drop-Casting Method: Roll-to-roll Nanoimprint Lithography
P2-36	10. Design Tools and Modeling	Yong-Won Ma	Pusan National University	kr	Multiple Laser Interference Exposure: Simulations and Experiments for the Fabrication of Wavy Patterns
P2-37	2. Electronic Materials for Interconnects and Packaging	Namhyun Kang	Pusan National University	kr	Interlayer materials to reduce transient liquid phase bonding time
P2-38	9. Reliability of Electronic Devices and Systems	SangHee Lee	Dankook University	kr	Preparation and Properties of Passivation Films Spray Coated on the Flexible Plastic Substrates
P2-39	9. Reliability of Electronic Devices and Systems	Seok Hwan Huh	Changwon National University	kr	SMT process effects on reliability of PCBs during biased HAST